

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method for plating on at least one conductive pattern on a first surface-side of a substrate and being electrically isolated from said substrate, said substrate having at least a first surface-side and a second surface-side, said method comprising the steps of:

placing the substrate on an electrode being part of a plating holder such that said second surface-side of said substrate is in electrical contact with said electrode ~~and said conductive pattern is temporarily electrically connected to said electrode~~; and

applying a plating solution on said first surface-side of said substrate ~~thereby and~~ inhibiting exposure of said second surface to said plating solution[.]; and

characterised in that said electrode and said conductive pattern are temporarily electrically connected by forming a polysilicon or an amorphous silicon conductor, which is insulated from said substrate and said plating solution, to temporarily connect said conductive pattern with a contact to the substrate, said contact being formed on the first surface-side of the substrate, and by providing an electrical connection between said contact and said electrode.

2. (Previously Presented) A method as recited in claim 1, wherein said conductive pattern is positioned on a first die and said contact is positioned on a second die different from said first die.

3. (Currently Amended) A method as recited in claim 2, wherein after said conductive pattern is plated, said method further comprises the step of dicing the substrate.

4. (Currently Amended) A method as in claim 1, wherein prior to applying the plating solution, a resist layer is deposited on said conductive pattern and patterned in order to create at least one covered area ~~an~~ and at least one uncovered area, said uncovered area being exposable to said plating solution.

5. (Previously Presented) A method as recited in claim 1, where said plating solution comprises an element selected from a group comprising Ag, Cu, Au, Pt, Ti, Ni and Co.

6. (Currently Amended) A substrate having at least a first surface and a second surface opposite to said first surface, said first surface being exposable to a plating solution, said substrate comprising

a conductive pattern being positioned at said first surface of a substrate;

a contact to the first surface of the substrate; and

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said conductive pattern being ~~temporarily~~ electrically connected by a polysilicon or an amorphous silicon conductor with said contact and said contact being electrically connected with said second surface and said polysilicon or amorphous silicon conductor being isolated from said substrate.
